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2 Abstract of the Disclosure
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4 The present invention relates to measures that enable simple assembly of a
5 high-frequency (HF) module. The HF module includes a HF circuit board (1), on
6 which at least one first antenna part (6) is located, a housing part (2), on which at
7 least one second antenna part (7) is located, and a shielding cover (3), whereby
8 the HF circuit board (1) is installed between the housing part (2) and the
9 shielding cover (3). With the aid of the measures according to the present
10 invention, the housing part (2) and the shielding cover (3) can be easily adjusted
11 relative to the HF circuit board (1). A reliable connection between these three
12 parts can also be achieved with relatively little outlay.

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14 To this end, the HF circuit board (1) includes, according to the present invention,
15 at least one through opening (8), while the housing part (2) has at least one peg
16 (10) which extends into the through opening (8). The peg (10) is connected with
17 the diametrically opposed surface (14) of the shielding cover (3).

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20 (Figure 1)
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